MAX-3D Path Finder
Complex placement, shortest path

Examples of 3D Path Finder capabilities

- Import Verilog or 2D floorplan
- Specify/modify 3D floorplan
- View 3D connections via fly-lines or actual routes
- Quickly route complex 3D busses
- Extract and simulate specified 3D nets
- Powerful PDN (power distribution network) generation

MAX-3D TSV Placer
Simplify TSV location / placement

- Automatically finds “holes” for TSVs
- Automatically optimizes and places TSVs
- Shows 3D connectivity with fly-lines
- Exports TSV data back into your 2D tools
The MAX-3D-Design Suite contains everything necessary to plan and lay out today’s complex wafer-stack and interposer multi-technology designs.

MMI’s suite of 3D tools includes DPC-SUE, MAX-3D, MAX-3D TSV Placer, and MAX-3D Path Finder.

- Load multiple chips in the same or different technologies
- Manage multiple levels of hierarchy and multiple tech files all at the same time
- Edit and view today’s largest designs
- Automatic Connectivity Tracing through multiple levels
- Show 3D connectivity with fly-lines
- Use your existing 2D Tech files
- View Results in 3D

**DPC-SUE** to import designs from either 2D floorplanner or block-level verilog; specify chip level, block size, connectivity; and export floorplan to MAX-3D.

**MAX-3D** for true 3-dimensional layout, supporting multiple distinct technology files for Through-Si Via 3D wafer-stack and interposer design.

**MAX-3D Path Finder**, to explore viability of interposer or stacked-die implementations.

**MAX-3D TSV Placer** for automatically locating, optimizing and placing TSVs.